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Part Number: [73944-6217](#)
Status: **Active**
Overview: [HDM® Backplane Connector System](#)
Description: HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 72 Circuits

Documents:

3D Model	Product Specification PS-73670-9999 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

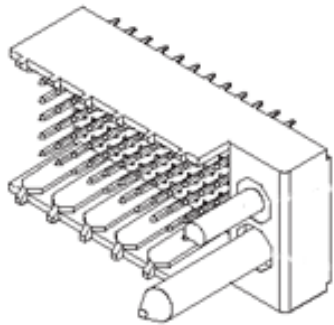
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73944
Application	Backplane
Component Type	PCB Header
Overview	HDM® Backplane Connector System
Product Name	HDM®
Style	N/A
UPC	800754841603

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	5.394/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	Yes
PCB Retention	None
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole



Series

image - Reference only

EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Low-Halogen Status
Low-Halogen

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73944Series](#)

Mates With

73632 HDM PLUS® Board-to-Board
Daughtercard Receptacle. 73780 HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	40
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	3
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

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